

# **MD1821**

## High-Speed 4-Channel MOSFET Driver with Inverting Outputs

#### Features

- Inverting MOSFET Driver
- 6 ns Rise and Fall Time
- 2A Peak Output Source and Sink Currents
- 1.8V to 5V Input CMOS Compatible
- 5V to 10V Total Supply Voltage
- · Smart Logic Threshold
- · Low-jitter Design
- Four Matched Channels
- Drives Two P-channel and Two N-channel MOSFETs
- Outputs can Swing below Ground
- Low-inductance Quad Flat No-lead Package
- · High-performance, Thermally Enhanced Package

#### Applications

- Medical Ultrasound Imaging
- Piezoelectric Transducer Drivers
- Non-destructive Testing (NDT)
- · PIN Diode Driver
- CCD Clock Driver/buffer
- High-speed Level Translator

#### **General Description**

The MD1821 is a high-speed, 4-channel MOSFET driver designed to drive high-voltage P-channel and N-channel MOSFETs for medical ultrasound applications and other applications requiring a high output current for a capacitive load. The high-speed input stage of the MD1821 can operate from a 1.8V to 5V logic interface with an optimum operating input signal range of 1.8V to 3.3V. An adaptive threshold circuit is used to set the level translator switch threshold to the average of the input logic 0 and logic 1 levels. The input logic levels may be ground referenced even though the driver is putting out bipolar signals. The level translator uses a proprietary circuit, which provides DC coupling together with high-speed operation.

The output stage of the MD1821 has separate power connections, enabling the output signal L and H levels to be chosen independently from the supply voltages used for the majority of the circuit. As an example, the input logic levels may be 0V and 1.8V, the control logic may be powered by +5 and -5V and the output L and H levels may be varied anywhere over the range of -5 to +5V. The output stage is capable of peak currents of up to ±2A, depending on the supply voltages used and load capacitance present. The PE pin serves a dual purpose. First, its logic H level is used to compute the threshold voltage level for the channel input level translators. Second, when PE is low, the outputs are disabled, with the A and C outputs high and the B and D outputs low. This assists in properly precharging the AC coupling capacitors that may be used in series in the gate drive circuit of an external PMOS and NMOS transistor pair.

#### Package Type



#### **Functional Block Diagrams**



### **Typical Application Circuit**



## 1.0 ELECTRICAL CHARACTERISTICS

#### Absolute Maximum Ratings†

Logic Supply Voltage, V <sub>DD</sub> –V <sub>SS</sub> Output High Supply Voltage, V <sub>H</sub> Output Low Supply Voltage, V <sub>I</sub>	V <sub>L</sub> –0.5V to V <sub>DD</sub> +0.5V
Low-side Supply Voltage, V <sub>SS</sub>	66 11
Logic Input Levels	
Maximum Junction Temperature, T <sub>J</sub>	+125°C
Operating Ambient Temperature, T <sub>A</sub>	–20°C to +85°C
Storage Temperature, T <sub>S</sub>	–65°C to +150°C
Package Power Dissipation:	
16-lead QFN	2.2W
ESD Rating (Note 1)	ESD Sensitive

**† Notice:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

**Note 1:** Device is ESD sensitive. Handling precautions are recommended.

#### DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $V_H = V_{DD} = 10V$ , $V_L = V_{SS} = GND = 0V$ , $V_{PE} = 3.3V$ , $T_A = 25^{\circ}C$										
Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions				
Logic Supply Voltage	V <sub>DD</sub> -V <sub>SS</sub>	4.75	-	11.5	V	$4V \le V_{DD} \le 11.5V$				
Low-side Supply Voltage	V <sub>SS</sub>	-5.5	_	0	V					
Output High Supply Voltage	V <sub>H</sub>	V <sub>SS</sub> +2		V <sub>DD</sub>	V					
Output Low Supply Voltage	VL	V <sub>SS</sub>		V <sub>DD</sub> –4	V					
V <sub>DD</sub> Quiescent Current	I <sub>DDQ</sub>	-	60		μA	No input transitions, PE = 0				
V <sub>H</sub> Quiescent Current	I <sub>HQ</sub>		2	—	μA					
V <sub>DD</sub> Quiescent Current	I <sub>DDQ</sub>		1.3	—	mA	No input transitions, PE = 1				
V <sub>H</sub> Quiescent Current	I <sub>HQ</sub>	-	2	—	μA					
V <sub>DD</sub> Average Current	I <sub>DD</sub>		3.5	—	mA	One channel on at 5 MHz, no load				
V <sub>H</sub> Average Current	Ι <sub>Η</sub>		10	—	mA	One channel on at 5 MHz, no load				
Input Logic Voltage High	V <sub>IH</sub>	V <sub>PE</sub> -0.3	_	V <sub>PE</sub>	V					
Input Logic Voltage Low	V <sub>IL</sub>	0	_	0.3	V	For logic inputs INA, INB, INC and				
Input Logic Current High	I <sub>IH</sub>	-	_	1	μA	IND				
Input Logic Current Low	۱ <sub>IL</sub>	-	_	1	μA					
PE Input logic Voltage High	V <sub>IH</sub>	1.7	3.3	5.25	V					
PE Input Logic Voltage Low	V <sub>IL</sub>	0	_	0.3	V	For logic input PE				
PE Input Resistance	R <sub>IN_PE</sub>	100	_	_	kΩ					
Logic Input Capacitance	C <sub>IN</sub>	_	5	10	pF					
Output Sink Resistance	R <sub>SINK</sub>	_	1.5		Ω	I <sub>SINK</sub> = 50 mA				
Output Source Resistance	R <sub>SOURCE</sub>	_	2		Ω	I <sub>SOURCE</sub> = 50 mA				
Peak Output Sink Current	I <sub>SINK</sub>	_	2		Α					
Peak Output Source Current	I <sub>SOURCE</sub>	—	2	—	Α					

### AC ELECTRICAL CHARACTERISTICS

<b>Electrical Specifications</b> : $V_H = V_{DD} = 10V$ , $V_L = V_{SS} = GND = 0V$ , $V_{PE} = 3.3V$ , $T_A = 25^{\circ}C$										
Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions				
Input or PE Rise and Fall Time	t <sub>irf</sub>		_	10	ns	Logic input edge speed requirement				
Propagation Delay when Output is from Low to High	t <sub>PLH</sub>		6.5		ns					
Propagation Delay when Output is from High to Low	t <sub>PHL</sub>		6.5		ns	C <sub>LOAD</sub> = 1000 pF (See <b>Timing</b> <b>Diagram</b> .), input signal rise/fall time 2 ns				
Output Rise Time	t <sub>r</sub>		7		ns	ume z ns				
Output Fall Time	t <sub>f</sub>		7		ns					
Rise and Fall Time Matching	l t <sub>r</sub> t <sub>f</sub> l		1		ns					
Propagation Low to High and High to Low Matching	l t <sub>PLH</sub> –t <sub>PHL</sub> l		1		ns	For each channel				
Propagation Delay Matching	$\Delta t_{dm}$		±2		ns	Device-to-device delay match				
PE On Time	t <sub>PE-ON</sub>		_	5	μs	V <sub>PE</sub> = 1.7V~5.25V,				
PE Off-time	t <sub>PE-OFF</sub>		_	4	μs	V <sub>DD</sub> = 7.5V~11.5V, –20°C~85°C				

### **TEMPERATURE SPECIFICATIONS**

Sym.	Min.	Тур.	Max.	Unit	Conditions		
TJ	—	_	+125	°C			
Τ <sub>Α</sub>	-20		+85	°C			
Τ <sub>S</sub>	-65		+150	°C			
PACKAGE THERMAL RESISTANCE							
$\theta_{JA}$		55	_	°C/W	Note 1		
	T <sub>J</sub> T <sub>A</sub> T <sub>S</sub>	T <sub>J</sub> — T <sub>A</sub> —20 T <sub>S</sub> —65	T <sub>J</sub> — — T <sub>A</sub> —20 — T <sub>S</sub> —65 —	T <sub>J</sub> — — +125 T <sub>A</sub> —20 — +85 T <sub>S</sub> —65 — +150	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		

**Note 1:** 1 oz four-layer 3" x 4" PCB

#### **Timing Diagram**



#### TABLE 1-1: TRUTH FUNCTION TABLE

	Logic Inputs	Out	puts	
PE	INA	INB	OUTA	OUTB
Н	L	L	V <sub>H</sub>	V <sub>H</sub>
Н	L	Н	V <sub>H</sub>	VL
Н	Н	L	VL	V <sub>H</sub>
Н	Н	Н	VL	VL
L	Х	Х	V <sub>H</sub>	VL
PE	INC	IND	OUTC	OUTD
н	L	L	V <sub>H</sub>	V <sub>H</sub>
Н	L	Н	V <sub>H</sub>	VL
Н	Н	L	VL	V <sub>H</sub>
Н	Н	н	VL	VL
L	Х	Х	V <sub>H</sub>	VL

#### 2.0 **PIN DESCRIPTION**

The details on the pins of MD1821 are listed on Table 2-1. See **Package Type** for the location of pins.

Pin Number	Pin Name	Description
1	INB	Logic input
2	VDD	High-side supply voltage
3	VSS	Low-side supply voltage. VSS is also connected to the IC substrate. It is required to connect to the most negative potential of voltage supplies.
4	INC	
5	IND	Logic input
6	GND	Logic input ground reference
7	VL	Supply voltage for N-channel output stage
8	OUTC	
9	OUTD	Output drivers
10, 11	VH	Supply voltage for P-channel output stage
12	OUTA	
13	OUTB	Output drivers
14	VL	Supply voltage for N-channel output stage
15	PE	Power enable logic input. When PE is high, the input logic threshold is set. When PE is low, all outputs are at default state and the IC is in Standby mode. (See Table 1-1 and Figure 3-1.)
16	INA	Logic input
Substrate		The IC substrate is internally connected to the thermal pad. The thermal pad and VSS must be connected externally.

TABLE 2-1: PIN FUNCTION TABLE

## 3.0 APPLICATION INFORMATION

For proper operation of the MD1821, low-inductance bypass capacitors should be used in the various supply pins. The GND pin should be connected to the logic ground. The INA, INB, INC, IND and PE pins should be connected to a logic source with a swing of GND to PE, where PE is 1.8V to 5V. Good trace practices should be followed corresponding to the desired operating speed. The internal circuitry of the MD1821 is capable of operating up to 100 MHz, with the primary speed limitation being the loading effects of the load capacitance. Because of this speed and the high transient currents due to capacitive loads, the bypass capacitors should be as close to the chip pins as possible. Unless the load specifically requires bipolar drive, the  $V_{SS}$  and  $V_L$  pins should have a low-inductance bypass capacitor to GND and supply power connections. If these voltages are not zero, they need bypass capacitors similar to the positive power supplies. The power connection  $V_{DD}$  should have a ceramic bypass capacitor to the ground plane with short leads and decoupling components to prevent resonance in the powerleads.



FIGURE 3-1: V<sub>TH</sub>/V<sub>PE</sub> Curve.





Timing Characteristics vs. Temperature and V<sub>DD</sub>.

The voltages of V<sub>H</sub> and V<sub>L</sub> decide the output signal levels. These two pins can draw fast transient currents of up to 2A, so they should be provided with an appropriate bypass capacitor located next to the chip pins. A ceramic capacitor of up to 1  $\mu$ F may be appropriate, with a series ferrite bead to prevent resonance in the power supply lead going to the capacitor. Pay particular attention to minimizing trace lengths, current loop area and using sufficient trace

width to reduce inductance. Surface-mount components are highly recommended. Since the output impedance of this driver is very low, in some cases, it may be desirable to add a small series resistor in series with the output signal to obtain better waveform transitions at the load terminals. This will reduce the output voltage slew rate at the terminals of a capacitive load. Make sure that parasitic couplings are minimized from the output to the input signal terminals. The parasitic feedback may cause oscillations or spurious waveform shapes on the edges of signal transitions. Since the input operates with signals down to 1.8V, even small coupled voltages may cause problems. The use of a solid ground plane and good power and signal layout practices will prevent this problem. Make sure that the circulating ground return current from a capacitive load will not react with common inductance to cause noise voltages in the input logic circuitry.

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#### 4.0 PACKAGING INFORMATION

#### 4.1 Package Marking Information



Legend	d: XXX Y YY WW NNN @3 *	Product Code or Customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC <sup>®</sup> designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
Note:	be carrie characters	nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available s for product code or customer-specific information. Package may or e the corporate logo.

#### 16-Lead QFN Package Outline (K6) 3.00x3.00mm body, 1.00mm height (max), 0.50mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Notes:

A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or 1. a printed indicator.

1.65

1.80

3.00

3.15\*

1.65

1.80

3.00

3.15\*

Depending on the method of manufacturing, a maximum of 0.15mm pullback (L1) may be present. 2. 3. The inner tip of the lead may be either rounded or square.

0.20

REF

					'						
Symb	ol	A	A1	A3	b	D	D2	E	E2	е	L
	MIN	0.80	0.00		0.18	2.85*	1.50	2.85*	1.50		0.20†

0.25

MAX 1.00 0.05 0.30 JEDEC Registration MO-220, Variation VEED-4, Issue K, June 2006.

\* This dimension is not specified in the JEDEC drawing.

0.90

0.02

† This dimension differs from the JEDEC drawing.

NOM

Drawings not to scale.

Dimension

(mm)

0.307

0.45

0.50

BSC

L1

0.00

-

0.15

θ

**0**0

-

14<sup>0</sup>

# MD1821

NOTES:

#### APPENDIX A: REVISION HISTORY

#### Revision A (May 2017)

- Converted Supertex Doc# DSFP-MD1821 to Microchip DS20005768A
- Changed the package marking format
- Changed the quantity of the K6 package from 3000/Reel to 3300/Reel
- Made minor text changes throughout the document

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To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO.	XX		- <u>x</u> - x	Exa	ample:	
Device	Package Options		Environmental Media Type		MD1821K6-G:	High-Speed 4-Channel MOSFET Driver with Inverting Outputs, 16-lead QFN, 3300/Reel
Device:	MD1821	=	High-Speed 4-Channel MOSFET Driver with Inverting Outputs			
Package:	K6	=	16-lead QFN			
Environmental:	G	=	Lead (Pb)-free/RoHS-compliant Package			
Media Type:	(blank)	=	3300/Reel for a K6 Package			

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